



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Kie Y. Ahn et al.

Title:

SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.:

303.672US1

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Examiner:

Group Art Unit: 1752

**Box Missing Parts** 

Commissioner for Patents Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

FEB 0 4 2002 TC 1700

A return postcard. <u>X</u>

 $\bar{\mathbf{x}}$ Power of Attorney by Assignee (1 Page).

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Box Issue Fee, Commissioner for Patents, Washington, D.C. 20231, on this 19 day of November, 2001.

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